

Title (en)
Method for via-pin filling

Title (de)
Verfahren zur Via-Stift-Verfüllung

Title (fr)
Procédé destiné au remplissage par crayon

Publication
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Application
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Abstract (en)
[origin: CN104703410A] The invention relates to a method for via-pin filling. A via hole is arranged in at least one first layer of a multi-layer circuit board. The method has following steps of: a) a pin is vertical to a first opening of the via hole for alignment; b) the pin penetrates through the first opening to be guided into the via hole; c) the pin is truncated at the length of the pin such that the length of the pin corresponds to the length of the via hole in a partially or wholly or manifold mode; d) by press fit between the first layer and a second layer, a first prepreg layer is arranged between the first layer and the second layer. According to the method provided by the invention, the method for filling the via hole through first layers of the multi-layer circuit board is improved such that the method is applied more quickly at the favorable cost with better quality.

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